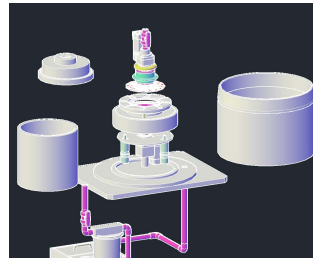


# Proposal of a New Type Plating Machine for Wafer



The main current plating machine is the vertical type, but the usability of the jig attached to the plating machine is very poor, and there are many problems..

- 1) Since it is eroded by the plating solution, the parts must always be exchanged.
- 2) Plating defect occurs due to poor energization.
- 3) It takes time to set wafers, the work does not proceed smoothly.
- 4) It is difficult to carry and move efficiently.

In addition, improvement of production efficiency is required by future high aspect countermeasure (supply of metal ions, uniform liquid flow) and improvement of uniform film thickness.

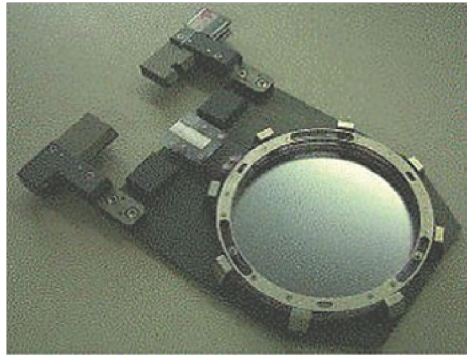
Therefore, we will propose the new type plating machine to solve these problems.



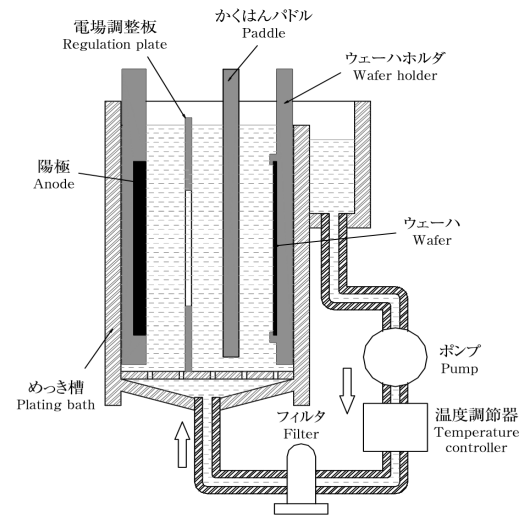
**GD LABORATORY**

Electroforming ,MEMS, Coating for  
Semiconductor

# Conventional

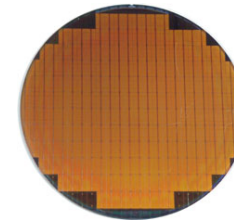


Jig

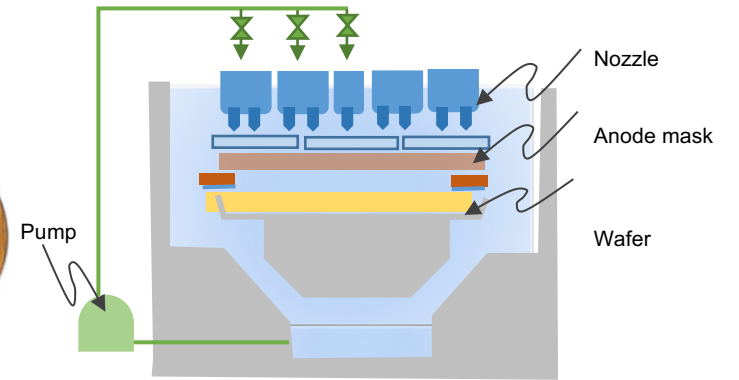


Vertical Type

# Proposal



Jig free



Horizontal Type

# Concept for New Plating Machine

